



Product data sheet

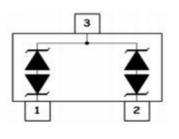
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PIN CONFIGURATION





S0T-23

FEATURES

- ♦IEC61000-4-2 (ESD) ±30kV (Contact) ±30kV (Air)
- ♦IEC61000-4-4 (EFT) 40A (5/50ηs)

- Low clamping voltage
- ♦Working voltages: 3.3V to 36V
- Low leakage current

MACHANICAL DATA

- **SOT-23** package
- ♦Flammability Rating: UL 94V-0
- High temperature soldering guaranteed: 260C/10s
- ♦Reel size: 7 inch
- ∻MSL 1

APPLICATIONS

- **Cell Phone Handsets and Accessories**
- Microprocessor based equipment
- Notebooks, Desktops, and Servers
- ♦Portable Instrumentation
- Networking and Telecom
- **Serial and Parallel Ports.**
- *Peripherals*

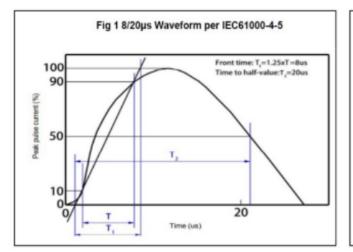
ABSOLUTE MAXIMUM RATING						
Symbol	Parameter	Value	Units			
N	ESD per IEC 61000-4-2 (Contact)	±30	1.3.7			
VESD	ESD per IEC 61000-4-2 (Air)	±30	kV			
PPP	Peak Pulse Power (8/20µs)	350	w			
Торт	Operating Temperature	-55/+150	D ₀			
T _{STG}	Storage Temperature	-55/+150	D ₀			
T∟	Lead Soldering Temperature	260 (10 sec.)	D			

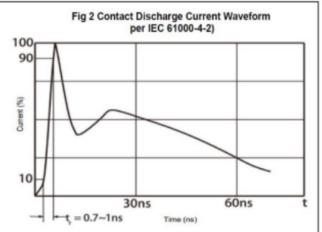


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ELECTRICAL CHARACTERISTICS (Tamb=25 ⁰ C)									
P/N	MARK	V _{RWM} (V) (max.)	V _₿ (V) (min.)	l⊤ (mA)	Vc@1A (V) (max.)	۷ (۱ (max.)	'c /) (@A)	I _ℝ (μΑ) (max.)	CJ (pF) (max.)
SM03C-MS	C03	3. 3	4.0	1	7.5	16. 0	20	40	450
SM05C-MS	C05	5.0	6. 0	1	9.8	18.0	17	10	200
SM08C-MS	C08	8. 0	8. 5	1	13. 4	24. 0	15	2	120
SM12C-MS	C12	12. 0	13. 3	1	19. 0	32. 0	11	1	75
SM15C-MS	C15	15. 0	16. 7	1	24. 0	38. 0	10	1	68
SM18C-MS	C18	18. 0	20. 0	1	29. 0	45. 0	9	1	57
SM20C-MS	C20	20. 0	22. 3	1	35. 0	50. 0	8	1	52
SM24C-MS	C24	24. 0	26. 7	1	43. 0	52. 0	7	1	50
SM36C-MS	C36	36. 0	40. 0	1	60. 0	75.0	4.5	1	35

ELECTRICAL CHARACTERISTICS CURVE





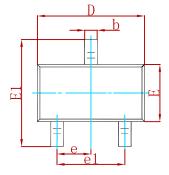
SMXXC-MS HF 🐼

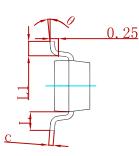
Semiconductor Compiance

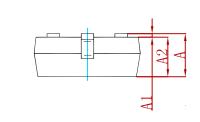




PACKAGE MECHANICAL DATA

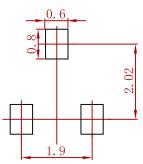






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SMXXC-MS	SOT-23	3000





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